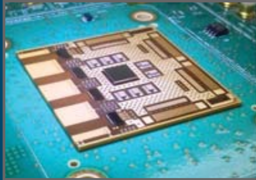
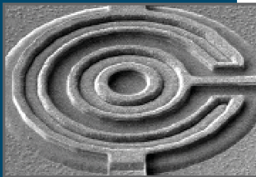
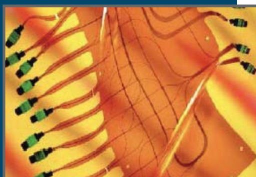
Advanced Packaging Update:

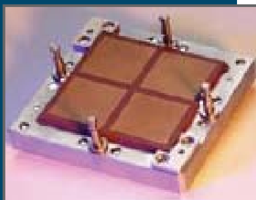
Market and Technology Trends

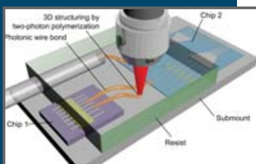
Vol. 3-0413











The third volume of the Advanced Packaging Update for 2012 provides TechSearch International's annual survey on IC package assembly price trends. Packages include QFPs, PBGAs, flip chip PBGAs, QFNs, and laminate CSPs. An analysis of cost saving trends, including the movement away from gold wire bonding is provided. The report details developments in glass interposers. Developments and roadmaps for photonic interconnects at the package, board, and board-to-board levels are highlighted. An economic outlook based on key economic indicators is provided.

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4801 Spicewood Springs Road • Suite 150
Austin, Texas 78759
Tel: 512-372-8887 • Fax: 512-372-8889
tsi@techsearchinc.com • www.techsearchinc.com

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